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FSBF15CH60BT Motion SPM[®] 3 Series

Features

- UL Certified No. E209204 (UL1557)
- 600 V 15 A 3-Phase IGBT Inverter with Integral Gate Drivers and Protection
- Low-Loss, Short-Circuit Rated IGBTs
- Built-In Bootstrap Diodes and Dedicated Vs Pins Simplify PCB Layout
- Separate Open-Emitter Pins from Low-Side IGBTs for Three-Phase Current Sensing
- Single-Grounded Power Supply
- Isolation Rating: 2500 V_{rms} / min.

Applications

• Motion Control - Home Appliance / Industrial Motor

Related Resources

• AN-9044 - Motion SPM® 3 Series Users Guide

General Description

FSBF15CH60BT is an advanced Motion SPM[®] 3 module providing a fully-featured, high-performance inverter output stage for AC Induction, BLDC, and PMSM motors. These modules integrate optimized gate drive of the built-in IGBTs to minimize EMI and losses, while also providing multiple on-module protection features including under-voltage lockouts, over-current shutdown, and fault reporting. The built-in, high-speed HVIC requires only a single supply voltage and translates the incoming logic-level gate inputs to the high-voltage, high-current drive signals required to properly drive the module's internal IGBTs. Separate negative IGBT terminals are available for each phase to support the widest variety of control algorithms.

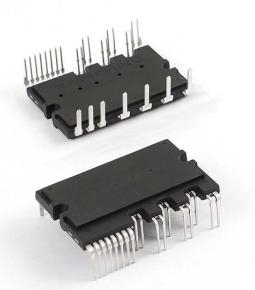


Figure 1. Package Overview

Package Marking and Ordering Information

Device	Device Marking	Package	Packing Type	Quantity
FSBF15CH60BT	FSBF15CH60BT	SPMJA-027	Rail	10

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January 2014

Integrated Power Functions

• 600 V - 15 A IGBT inverter for three-phase DC / AC power conversion (please refer to Figure 3)

Integrated Drive, Protection, and System Control Functions

- For inverter high-side IGBTs: gate drive circuit, high-voltage isolated high-speed level shifting control circuit Under-Voltage Lock-Out Protection (UVLO)
 Note: Available bootstrap circuit example is given in Figures 12 and 13.
- For inverter low-side IGBTs: gate drive circuit, Short-Circuit Protection (SCP)
 control supply circuit Under-Voltage Lock-Out Protection (UVLO)
- Fault signaling: corresponding to UVLO (low-side supply) and SC faults
- Input interface: active-HIGH interface, works with 3.3 / 5 V logic, Schmitt-trigger input

Pin Configuration

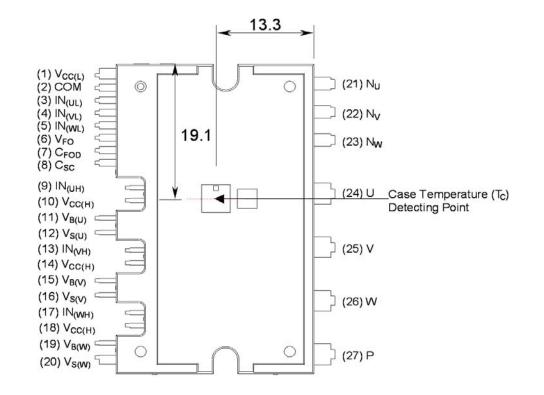


Figure 2. Top View

Pin Number	Pin Name	Pin Description
1	V _{CC(L)}	Low-Side Common Bias Voltage for IC and IGBTs Driving
2	COM	Common Supply Ground
3	IN _(UL)	Signal Input for Low-Side U-Phase
4	IN _(VL)	Signal Input for Low-Side V-Phase
5	IN _(WL)	Signal Input for Low-Side W-Phase
6	V _{FO}	Fault Output
7	C _{FOD}	Capacitor for Fault Output Duration Selection
8	C _{SC}	Capacitor (Low-Pass Filter) for Short-Circuit Current Detection Input
9	IN _(UH)	Signal Input for High-Side U-Phase
10	V _{CC(H)}	High-Side Common Bias Voltage for IC and IGBTs Driving
11	V _{B(U)}	High-Side Bias Voltage for U-Phase IGBT Driving
12	V _{S(U)}	High-Side Bias Voltage Ground for U-Phase IGBT Driving
13	IN _(VH)	Signal Input for High-Side V-Phase
14	V _{CC(H)}	High-Side Common Bias Voltage for IC and IGBTs Driving
15	V _{B(V)}	High-Side Bias Voltage for V-Phase IGBT Driving
16	V _{S(V)}	High-Side Bias Voltage Ground for V Phase IGBT Driving
17	IN _(WH)	Signal Input for High-Side W-Phase
18	V _{CC(H)}	High-Side Common Bias Voltage for IC and IGBTs Driving
19	V _{B(W)}	High-Side Bias Voltage for W-Phase IGBT Driving
20	V _{S(W)}	High-Side Bias Voltage Ground for W-Phase IGBT Driving
21	NU	Negative DC-Link Input for U-Phase
22	N _V	Negative DC-Link Input for V-Phase
23	N _W	Negative DC-Link Input for W-Phase
24	U	Output for U-Phase
25	V	Output for V-Phase
26	W	Output for W-Phase
27	Р	Positive DC-Link Input

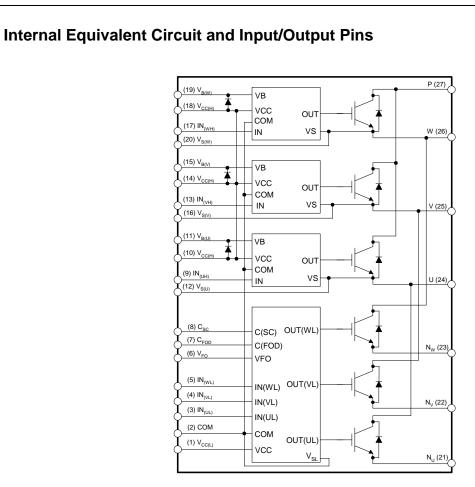


Figure 3. Internal Block Diagram

1st Notes:

1. Inverter low-side is composed of three IGBTs, freewheeling diodes for each IGBT, and one control IC. It has gate drive and protection functions.

2. Inverter power side is composed of four inverter DC-link input terminals and three inverter output terminals.

3. Inverter high-side is composed of three IGBTs, freewheeling diodes, and three drive ICs for each IGBT.

Absolute Maximum Ratings ($T_J = 25^{\circ}C$, unless otherwise specified.)

Inverter Part

Symbol	Parameter	Conditions	Rating	Unit
V _{PN}	Supply Voltage	Applied between P - N _U , N _V , N _W	450	V
V _{PN(Surge)}	Supply Voltage (Surge)	Applied between P - N _U , N _V , N _W	500	V
V _{CES}	Collector - Emitter Voltage		600	V
± I _C	Each IGBT Collector Current	$T_C = 25^{\circ}C, \ T_J \leq 150^{\circ}C$	15	А
± I _{CP}	Each IGBT Collector Current (Peak)	T_C = 25°C, $T_J \leq$ 150°C, Under 1 ms Pulse Width	30	A
P _C	Collector Dissipation	T _C = 25°C per Chip	25	W
TJ	Operating Junction Temperature	(2nd Note 1)	- 40 ~ 150	°C

2nd Notes:

1. The maximum junction temperature rating of the power chips integrated within the Motion SPM[®] 3 product is 150°C (at T_C \leq 125°C).

Control Part

Symbol	Parameter	Conditions	Rating	Unit
V _{CC}	Control Supply Voltage	Applied between V _{CC(H)} , V _{CC(L)} - COM	20	V
V _{BS}	High-Side Control Bias Voltage	Applied between V_B(U) - V_S(U), V_B(V) - V_S(V), V_B(W) - V_S(W)	20	V
V _{IN}	Input Signal Voltage	Applied between IN _(UH) , IN _(VH) , IN _(WH) , IN _(WH) , IN _(UL) , IN _(VL) , IN _(WL) - COM	-0.3 ~ V _{CC} + 0.3	V
V _{FO}	Fault Output Supply Voltage	Applied between V _{FO} - COM	$-0.3 \sim V_{CC} + 0.3$	V
I _{FO}	Fault Output Current	Sink Current at V _{FO} pin	5	mA
V _{SC}	Current-Sensing Input Voltage	Applied between C _{SC} - COM	-0.3 ~ V _{CC} + 0.3	V

Bootstrap Diode Part

Symbol	Parameter	Conditions	Rating	Unit
V _{RRM}	Maximum Repetitive Reverse Voltage		600	V
۱ _F	Forward Current	$T_C = 25^{\circ}C, \ T_J \leq 150^{\circ}C$	0.5	А
I _{FP}	Forward Current (Peak)	T_C = 25°C, $T_J \leq$ 150°C $$ Under 1 ms Pulse Width	2.0	A
TJ	Operating Junction Temperature		-40 ~ 150	°C

Total System

Symbol	Parameter	Conditions	Rating	Unit
V _{PN(PROT)}	Self-Protection Supply Voltage Limit (Short-Circuit Protection Capability)	$V_{CC} = V_{BS} = 13.5 \sim 16.5 \text{ V}$ T _J = 150°C, Non-Repetitive, < 2 µs	400	V
T _C	Module Case Operation Temperature	-40°C $\leq T_J \leq$ 150°C, See Figure 2	-40 ~ 125	°C
T _{STG}	Storage Temperature		-40 ~ 125	°C
V _{ISO}	Isolation Voltage	60 Hz, Sinusoidal, AC 1 Minute, Connect Pins to Heat Sink Plate	2500	V _{rms}

Thermal Resistance

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{th(j-c)Q}	Junction to Case Thermal Resistance	Inverter IGBT Part (per 1 / 6 module)	-	-	4.9	°C / W
R _{th(j-c)F}		Inverter FWDi Part (per 1 / 6 module)	-	-	5.7	°C / W

2nd Notes:

2. For the measurement point of case temperature (T $_{C}),$ please refer to Figure 2.

Electrical Characteristics ($T_J = 25^{\circ}C$, unless otherwise specified.)

Inverter Part

S	ymbol	Parameter	Condi	tions	Min.	Тур.	Max.	Unit
V	CE(SAT)	Collector - Emitter Saturation Voltage	V _{CC} = V _{BS} = 15 V V _{IN} = 5 V	I _C = 15 A, T _J = 25°C			2.2 V	
	V _F	FWDi Forward Voltage	$V_{IN} = 0 V$	I _F = 15 A, T _J = 25°C	-	-	2.5	V
HS	t _{ON}	Switching Times		$V_{PN} = 300 \text{ V}, V_{CC} = V_{BS} = 15 \text{ V}$		0.75	-	μS
	t _{C(ON)}		$I_C = 15 \text{ A}$ $V_{IN} = 0 \text{ V} \leftrightarrow 5 \text{ V}$, Inductive Load (2nd Note 3)		-	0.20	-	μS
	t _{OFF}				-	0.55	-	μS
	t _{C(OFF)}				-	0.10	-	μS
	t _{rr}				-	0.10	-	μS
LS	t _{ON}		V_{PN} = 300 V, V_{CC} = V_B	_S = 15 V	-	0.45	-	μS
	t _{C(ON)}		$I_{C} = 15 \text{ A}$ $V_{IN} = 0 \text{ V} \leftrightarrow 5 \text{ V}$, Induc	tive Load	-	0.25	-	μS
	t _{OFF}		(2nd Note 3)		-	0.55	-	μS
	t _{C(OFF)}				-	0.10	-	μS
	t _{rr}]			-	0.10	-	μS
	I _{CES}	Collector - Emitter Leakage Current	$V_{CE} = V_{CES}$		-	-	1	mA

2nd Notes:

3. t_{ON} and t_{OFF} include the propagation delay of the internal drive IC. t_{C(ON)} and t_{C(OFF)} are the switching time of IGBT itself under the given gate driving condition internally. For the detailed information, please see Figure 4.

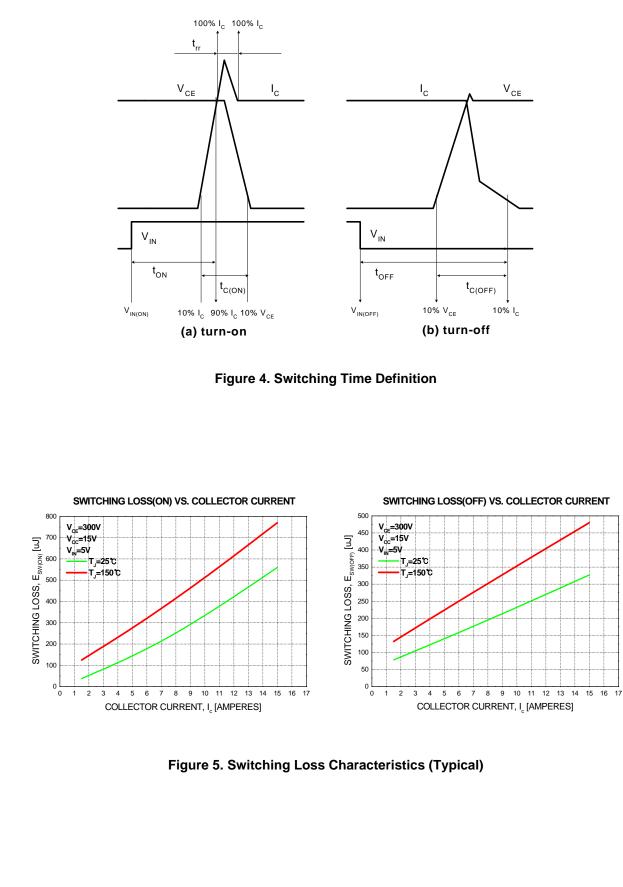
Control Part

Symbol	Parameter	Cond	Conditions		Тур.	Max.	Unit
IQCCL	Quiescent V _{CC} Supply Current	V _{CC} = 15 V IN _(UL, VL, WL) = 0 V	CC(L) - COM	-	-	23	mA
I _{QCCH}		$V_{CC} = 15 V$ $IN_{(UH, VH, WH)} = 0 V$	_{CC(H)} - COM	-	-	600	μA
I_{QBS}	Quiescent V _{BS} Supply Current	$V_{BS} = 15 V$ V IN _(UH, VH, WH) = 0 V V	$B(U) - V_{S(U)}, V_{B(V)} - V_{S(V)}, B(W) - V_{S(W)}$	-	-	500	μA
V _{FOH}	Fault Output Voltage	V _{SC} = 0 V, V _{FO} Circuit:	4.7 k Ω to 5 V Pull-up	4.5	-	-	V
V _{FOL}		V_{SC} = 1 V, V_{FO} Circuit: 4.7 k Ω to 5 V Pull-up		-	-	0.8	V
V _{SC(ref)}	Short-Circuit Current Trip Level	V _{CC} = 15 V (2nd Note 4)		0.45	0.50	0.55	V
TSD	Over-Temperature Protection	Temperature at LVIC		-	160	-	°C
∆TSD	Over-Temperature Protection Hysterisis	Temperature at LVIC		-	5	-	°C
UV _{CCD}	Supply Circuit	Detection Level		10.7	11.9	13.0	V
UV _{CCR}	Under-Voltage Protection	Reset Level		11.2	12.4	13.4	V
UV _{BSD}]	Detection Level		10	11	12	V
UV _{BSR}]	Reset Level		10.5	11.5	12.5	V
t _{FOD}	Fault-Out Pulse Width	C _{FOD} = 33 nF (2nd Note 5)		1.0	1.8	-	ms
V _{IN(ON)}	ON Threshold Voltage		$_{\rm H}$, IN _(VH) , IN _(WH) , IN _(UL) ,	2.8	-	-	V
V _{IN(OFF)}	OFF Threshold Voltage	IN _(VL) , IN _(WL) - COM		-	-	0.8	V

2nd Notes:

4. Short-circuit protection is functioning only at the low-sides.

5. The fault-out pulse width t_{FOD} depends on the capacitance value of C_{FOD} according to the following approximate equation: $C_{FOD} = 18.3 \times 10^{-6} \times t_{FOD}$ [F]



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Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
V _F	Forward Voltage	I _F = 0.1 A, T _C = 25°C	-	2.5	-	V
t _{rr}	Reverse-Recovery Time	I _F = 0.1 A, T _C = 25°C	-	80	-	ns

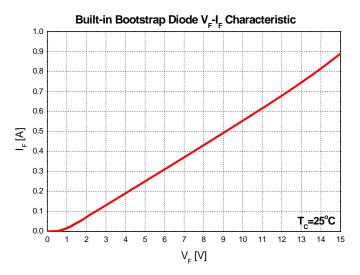


Figure 6. Built-in Bootstrap Diode Characteristics

2nd Notes:

6. Built-in bootstrap diode includes around 15 $\ensuremath{\Omega}$ resistance characteristic.

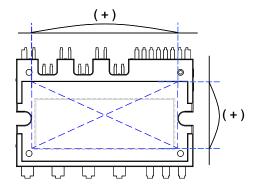
Recommended Operating Conditions

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
V _{PN}	Supply Voltage	Applied between P - N _U , N _V , N _W	-	300	400	V
V _{CC}	Control Supply Voltage	Applied between V _{CC(H)} , V _{CC(L)} - COM	13.5	15.0	16.5	V
V _{BS}	High-Side Bias Voltage	Applied between V _{B(U)} - V _{S(U)} , V _{B(V)} - V _{S(V)} , V _{B(W)} - V _{S(W)}	13.0	15.0	18.5	V
dV _{CC} / dt, dV _{BS} / dt	Control Supply Variation		-1	-	1	V / μs
t _{dead}	Blanking Time for Preventing Arm-Short	Each Input Signal	2	-	-	μS
f _{PWM}	PWM Input Signal	$-40^{\circ}C \leq T_C \leq 125^{\circ}C, \ -40^{\circ}C \leq T_J \leq 150^{\circ}C$	-	-	20	kHz
V _{SEN}	Voltage for Current Sensing	Applied between N _U , N _V , N _W - COM (Including Surge Voltage)	-4		4	V

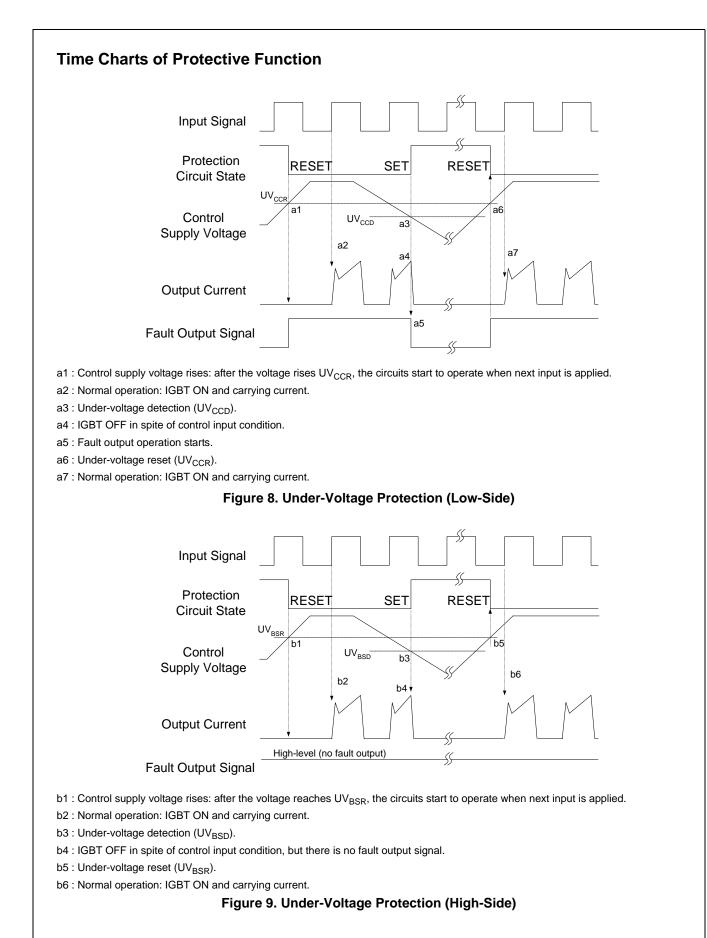
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Mechanical Characteristics and Ratings

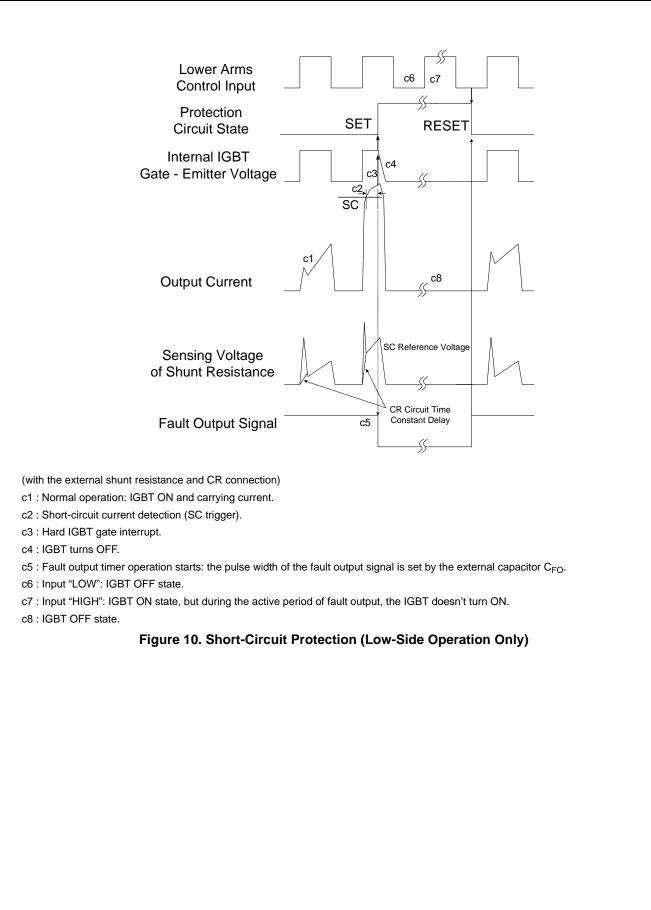
Paramete	er	Conditions		Min.	Тур.	Max.	Unit
Mounting Torque		Mounting Screw: M3	Recommended 0.62 N•m	0.51	0.62	1.00	N∙m
Device Flatness			See Figure 7	0	-	+120	μm
Weight				-	15.40	-	g







FSBF15CH60BT Motion SPM® 3 Series



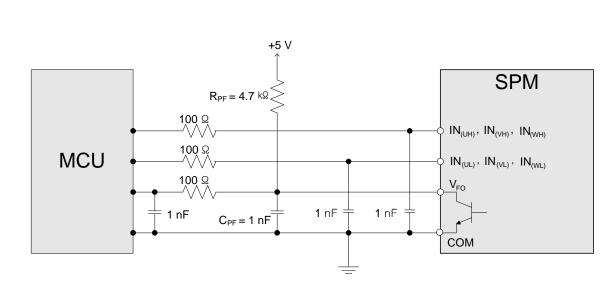
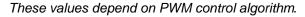
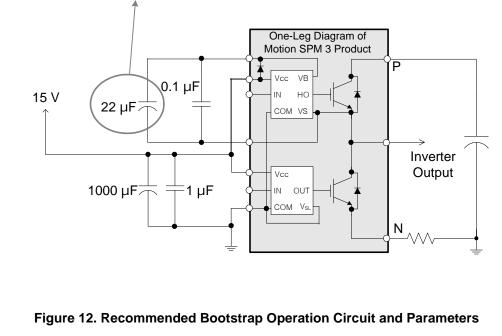


Figure 11. Recommended MCU I/O Interface Circuit

3rd Notes:

- 1. RC coupling at each input might change depending on the PWM control scheme in the application and the wiring impedance of the application's printed circuit board. The input signal section of the Motion SPM[®] 3 product integrates a 5 kΩ (typ.) pull-down resistor. Therefore, when using an external filtering resistor, please pay attention to the signal voltage drop at input terminal.
- 2. The logic input works with standard CMOS or LSTTL outputs.





3rd Notes:

3. The ceramic capacitor placed between V_{CC} - COM should be over 1 µF and mounted as close to the pins of the Motion SPM 3 product as possible.

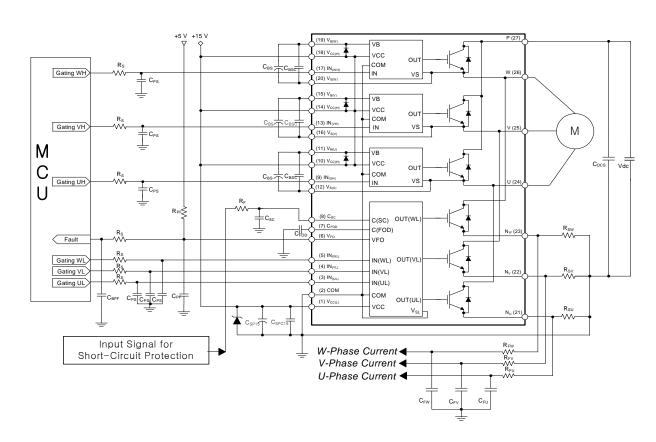
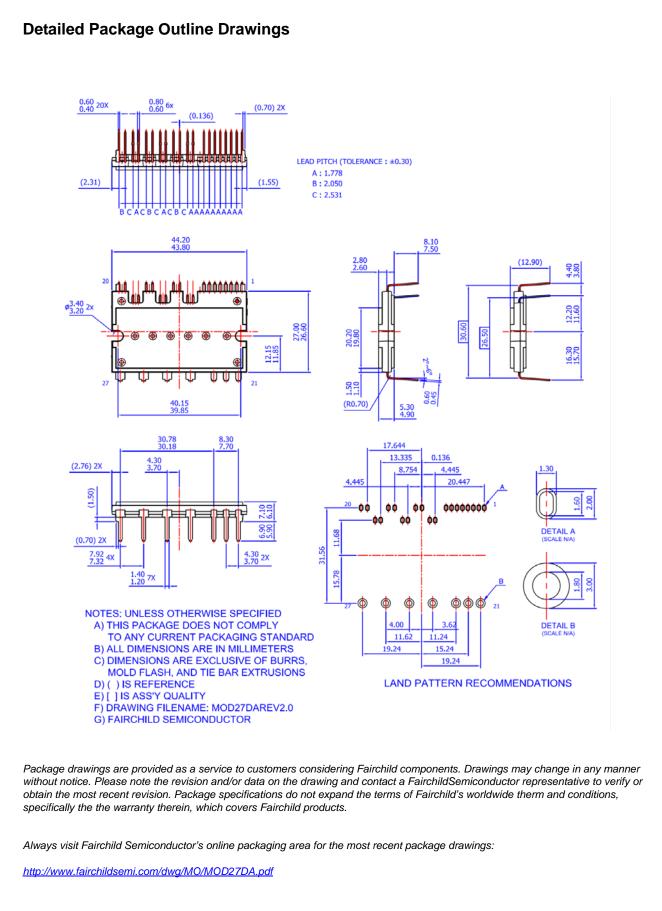


Figure 13. Typical Application Circuit

4th Notes:

- 1. To avoid malfunction, the wiring of each input should be as short as possible (less than 2 3cm).
- 2. By virtue of integrating an application-specific type of HVIC inside the Motion SPM[®] 3 product, direct coupling to MCU terminals without any optocoupler or transformer isolation is possible.
- 3. V_{FO} output is open-collector type. This signal line should be pulled up to the positive side of the 5 V power supply with approximately 4.7 k Ω resistance (please refer to Figure 11).
- 4. C_{SP15} of around seven times larger than bootstrap capacitor C_{BS} is recommended.
- 5. V_{FO} output pulse width should be determined by connecting an external capacitor (C_{FOD}) between C_{FOD} (pin 7) and COM (pin 2). (Example: if C_{FOD} = 33 nF, then t_{FO} = 1.8 ms (typ.)) Please refer to the 2nd note 5 for calculation method.
- Input signal is active-HIGH type. There is a 5 kΩ resistor inside the IC to pull down each input signal line to GND. RC coupling circuits should be used to prevent input signal oscillation. R_SC_{PS} time constant should be selected in the range 50 ~ 150 ns. C_{PS} should not be less than 1 nF (recommended R_S = 100 Ω, C_{PS} = 1 nF).
- 7. To prevent errors of the protection function, the wiring around R_F and C_{SC} should be as short as possible.
- In the short-circuit protection circuit, please select the R_FC_{SC} time constant in the range 1.5 ~ 2.0 μs.
 Each capacitor should be mounted as close to the pins of the Motion SPM 3 product as possible.
- 10. To prevent surge destruction, the wiring between the smoothing capacitor and the P & GND pins should be as short as possible. The use of a high-frequency non-inductive capacitor of around 0.1 ~ 0.22 µF between the P & GND pins is recommended.
- Relays are used in almost every systems of electrical equipment in home appliances. In these cases, there should be sufficient distance between the MCU and the relays.
 C_{SPC15} should be over 1 µF and mounted as close to the pins of the Motion SPM 3 product as possible.



FSBF15CH60BT Motion SPM® 3 Series



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